

# Pelnox®

<b>Product Name</b>	ME-5131 LC
<b>Product Category</b>	One Component Type Resin
<b>Usage</b>	General Modules
<b>Function</b>	One Component, Low Temperature Curing, Moisture Resistant, Fast Curing

## As supplied

(Typical Value)

Item	Condition	Unit	ME-5131 LC
<b>Appearance</b>	visual	–	Black liquid
<b>Specific Gravity</b>	25°C	–	1.57
<b>Viscosity</b>	25°C	mPa·s	40,000
<b>Gel Time</b>	73°C 5g	minutes	17

**Standard Curing Condition    73°C x 120 minutes**

## As cured

Item	Condition	Unit	Typical Value
<b>Hardness</b>	JIS K 7215 25°C	Shore D	90
<b>Glass Transition Temperature</b>	TMA	°C	89
<b>Coefficient of Thermal Expansion</b>	below Tg	10 <sup>-5</sup> /°C	4.7
	above Tg	10 <sup>-5</sup> /°C	12.4
<b>Shear Adhesive Strength</b>	JIS K 6850 25°C (SUS-SUS)	MPa	14
	120°C 95%RH 24hrs 25°C (SUS-SUS)	MPa	11
<b>Flexural Strength</b>	JIS K 6911 25°C thickness:2mm	MPa	87
<b>Flexural Modulus</b>	JIS K 6911 25°C thickness:2mm	MPa	5,630
<b>Tensile Strength</b>	JIS K 7161 25°C tensile speed 10mm/min	MPa	51
<b>Tensile Modulus</b>	JIS K 7161 25°C tensile speed 10mm/min	MPa	3,288
<b>Volume Resistivity</b>	JIS K 6911 25°C	Ω-cm	1.2 x 10 <sup>16</sup>
	JIS K 6911 boil for 2hrs	Ω-cm	3.9 x 10 <sup>15</sup>
<b>Water Absorption</b>	JIS K 6911 boil for 2hrs	wt%	0.5
<b>Cure Shrinkage</b>	14×120×12.5(mm) 25g	%	0.6
<b>Thermal Conductivity</b>	Quick Thermal Conductivity Meter	W/mk	0.8
<b>Storage Modulus</b>	DMA 25°C 1Hz 5°C/min	GPa	3.6
<b>E'' Peak Top</b>	DMA	°C	147
<b>tanδ Peak Top</b>	DMA	°C	153
<b>Breakdown Voltage</b>	JIS K 6911 25°C	kV/mm	18.0

The above values are typical and not specification



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